T-1 (3mm) BI-LEVEL LED INDICATOR

Part Number: L-93A8AFQ/2ID-RV

High Efficiency Red

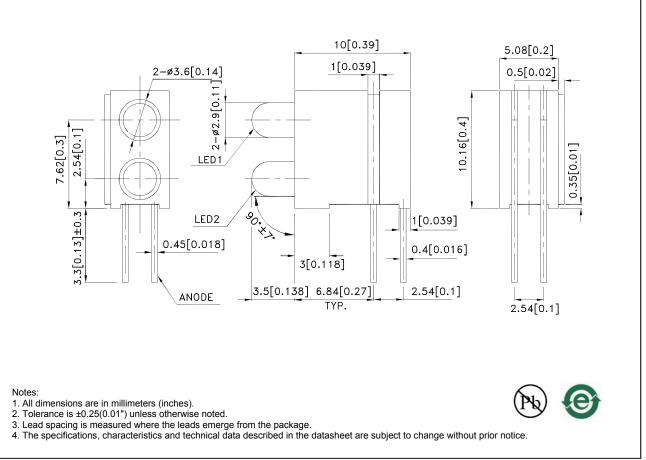
Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



SPEC NO: DSAC6304 APPROVED: WYNEC REV NO: V.4A CHECKED: Allen Liu DATE: DEC/18/2011 DRAWN: D.M.Su

Selection Guide lv (mcd) [2] Viewing @ 10mA Angle [1] Lens Type Part No. Dice Min. 201/2 Тур. 12 25 L-93A8AFQ/2ID-RV High Efficiency Red (GaAsP/GaP) Red Diffused 60° *12 *6

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.		Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627	*627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625	*617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45			nm	I⊧=20mA
С	Capacitance	High Efficiency Red	1	5		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	:	2	2.5	V	IF=20mA
lr	Reverse Current	High Efficiency Red			10	uA	VR = 5V

Notes: 1.Wavelength: +/-1nm.

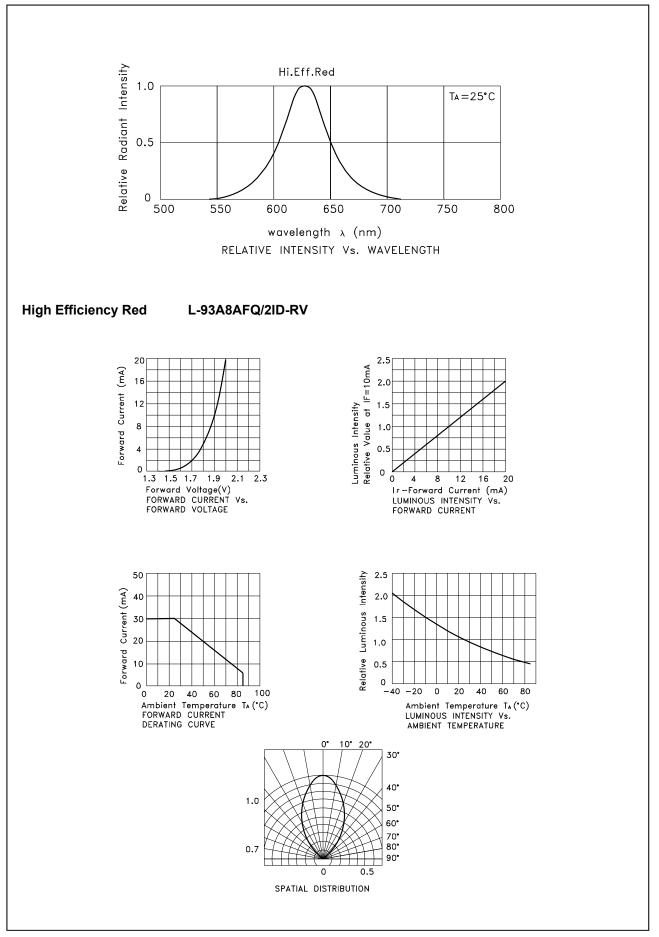
Forward Voltage: +/-0.1V.
*Wavelength value is traceable to the CIE127-2007 compliant national standards.

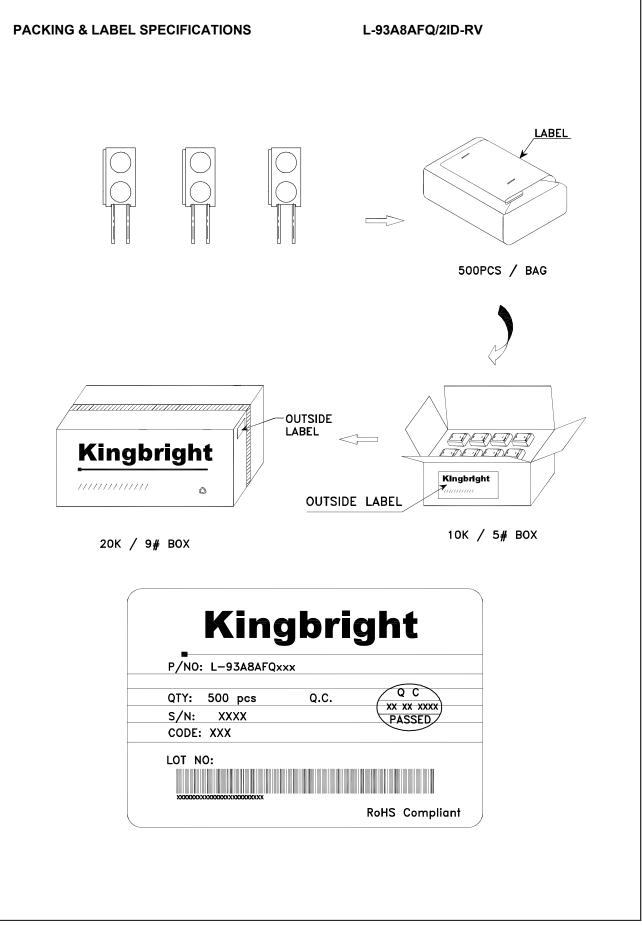
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	160	mA			
Reverse Voltage	5	V			
Operating/Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

Notes:

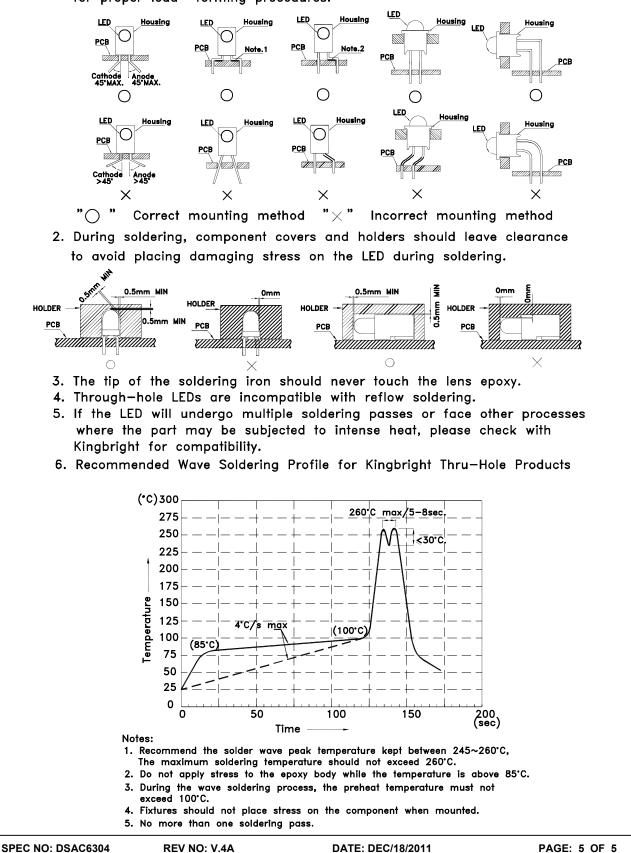
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



CHECKED: Allen Liu